

## ESPI Current Report

**Number:** 7/2021  
**Date:** 31 May 2021  
**Company:** XTPL S.A., a joint stock company with its registered office in Wrocław

**Topic:** Signing the grant agreement.

**Legal basis:** Article 17(1) MAR – inside information

**Contents of the Report:** In relation to the ESPI Current Report No. 3/2021 of 9 April 2021, the Management Board of XTPL S.A. (the “Issuer”) announces that today (31 May 2021) it has received information that on 28 May 2021 the National Centre for Research and Development (“NCBR”) signed an agreement on co-financing, under the 6/1.1.1/2020 – “Fast Track” competition organized by NCBR, for the Issuer’s project “Development of breakthrough printing technology of 3D micrometric conductive structures using an innovative printhead capable of printing on non-planar substrates and compatible ink for printed electronics applications” (the “Project”).

The scope of this project is the design and implementation of the new technology for printing of ultrafine conductive structures on 3D substrates for applications in printed electronics.

- Total Project value: PLN 11,615,569.56;
- Recommended co-financing value: PLN 7,695,844.09;
- Implementation period: 1 October 2020 – 30 September 2023

In the opinion of the Issuer’s Management Board the above fact is inside information, as grants constitute an important element of financing the Issuer’s operations. The Project will contribute to further development of the Issuer’s strategic area of printed electronics.

### Signatures of the Company’s representatives:

Jacek Olszański  
MANAGEMENT BOARD MEMBER